


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/22/13482	
1.3 Title of PCN	STM32G0B0x, STM32G0B1x and STM32G0C1x 512K - product enhancement	
1.4 Product Category	STM32G0B0x, STM32G0B1x, STM32G0C1x	
1.5 Issue date	2022-06-28	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
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2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	TSMC FAB14 (Taiwan)

4. Description of change

	Old	New
4.1 Description	<p>STM32G0B0x, STM32G0B1x and STM32G0C1x - (Die467- cut1.0 revision A) product has limitation as described in Errata Sheets.</p> <ul style="list-style-type: none"> - ES0547 (Rev 1 - January 12 2021) for STM32G0B0CE/KE/RE/VE device - ES0548 (Rev 1 - January 12 2021) for STM32G0B1xB/xC/xE device - ES0549 (Rev 1 - January 12 2021) for STM32G0C1xC/xE device <p>Limitations:</p> <ul style="list-style-type: none"> - Device lock in case of OPT bytes mismatch - Flash memory PCROP area weakness - SRAM contents corrupted upon entry in Standby - ADC Offset calibration improvements - Wakeup capability GPIO's not configurable after wakeup 	<p>STM32G0B0x, STM32G0B1x and STM32G0C1x 512K (Die467- cut1.1 revision Z) product enhancement fixes those limitations as described in Errata Sheet.</p> <ul style="list-style-type: none"> - ES0547 (Rev 2 - April 11 2022) for STM32G0B0CE/KE/RE/VE device - ES0548 (Rev 2 - April 11 2022) for STM32G0B1xB/xC/xE device - ES0549 (Rev 2 - April 11 2022) for STM32G0C1xC/xE device <p>Enhancements:</p> <ul style="list-style-type: none"> - Device lock in case of OPT bytes mismatch - fixed - Flash memory PCROP area weakness – fixed - TIM16 and TIM17 are unduly clocked by SYSCLK – fixed - ADC Offset calibration improved - Wakeup capability GPIO's not configurable after wakeup - fixed - Device IDCODE updated
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement as indicated in Errata Sheets: ES0547, ES0548 & ES0549	

5. Reason / motivation for change

5.1 Motivation	The strategy of ST GPM Division is to increase the robustness and improve performances, quality and functionality of our products. This is achieved by introducing new die revision for STM32G0B0x , STM32G0B1x and STM32G0Cx products.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools. Die revision changes from "A" to "Z" on Package Marking
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7. Timing / schedule	
7.1 Date of qualification results	2022-06-30
7.2 Intended start of delivery	2022-08-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation		
8.1 Description	13482 MDG-MCD-RER1918_STM32G0Bx_Die 467_Reliability Evaluation Report_rev1.4.pdf	
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date
		2022-06-28

9. Attachments (additional documentations)
13482 Public product.pdf 13482 MDG-MCD-RER1918_STM32G0Bx_Die 467_Reliability Evaluation Report_rev1.4.pdf 13482 PCN13482_Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32G0B1RBI3N	

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